



element14

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the manufacturer

**DE**

Dieses Datenblatt wird vom  
Hersteller bereitgestellt

**FR**

Cette fiche technique est  
présentée par le fabricant

# 2N4401

## General Purpose Transistors

### NPN Silicon

#### Features

- Pb-Free Packages are Available\*

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	$V_{CEO}$	40	Vdc
Collector – Base Voltage	$V_{CBO}$	60	Vdc
Emitter – Base Voltage	$V_{EBO}$	6.0	Vdc
Collector Current – Continuous	$I_C$	600	mA dc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	625 5.0	mW mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

#### THERMAL CHARACTERISTICS

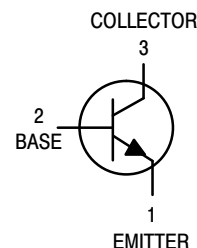
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	$^\circ\text{C/W}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

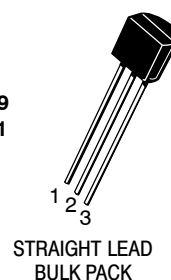


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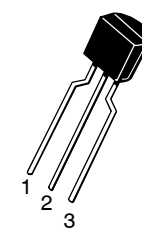
<http://onsemi.com>



TO-92  
CASE 29  
STYLE 1

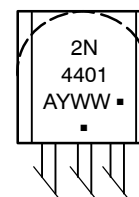


STRAIGHT LEAD  
BULK PACK



BENT LEAD  
TAPE & REEL  
AMMO PACK

#### MARKING DIAGRAM



2N4401 = Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## 2N4401

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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#### OFF CHARACTERISTICS

Collector–Emitter Breakdown Voltage (Note 1)	( $I_C = 1.0\text{ mA}$ , $I_B = 0$ )	$V_{(BR)CEO}$	40	–	Vdc
Collector–Base Breakdown Voltage	( $I_C = 0.1\text{ mA}$ , $I_E = 0$ )	$V_{(BR)CBO}$	60	–	Vdc
Emitter–Base Breakdown Voltage	( $I_E = 0.1\text{ mA}$ , $I_C = 0$ )	$V_{(BR)EBO}$	6.0	–	Vdc
Base Cutoff Current	( $V_{CE} = 35\text{ Vdc}$ , $V_{EB} = 0.4\text{ Vdc}$ )	$I_{BEV}$	–	0.1	$\mu\text{Adc}$
Collector Cutoff Current	( $V_{CE} = 35\text{ Vdc}$ , $V_{EB} = 0.4\text{ Vdc}$ )	$I_{CEX}$	–	0.1	$\mu\text{Adc}$

#### ON CHARACTERISTICS (Note 1)

DC Current Gain	( $I_C = 0.1\text{ mA}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 1.0\text{ mA}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 10\text{ mA}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 150\text{ mA}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 500\text{ mA}$ , $V_{CE} = 2.0\text{ Vdc}$ )	$h_{FE}$	20 40 80 100 40	– – – 300 –	–
Collector–Emitter Saturation Voltage	( $I_C = 150\text{ mA}$ , $I_B = 15\text{ mA}$ ) ( $I_C = 500\text{ mA}$ , $I_B = 50\text{ mA}$ )	$V_{CE(sat)}$	– –	0.4 0.75	Vdc
Base–Emitter Saturation Voltage	( $I_C = 150\text{ mA}$ , $I_B = 15\text{ mA}$ ) ( $I_C = 500\text{ mA}$ , $I_B = 50\text{ mA}$ )	$V_{BE(sat)}$	0.75 –	0.95 1.2	Vdc

#### SMALL–SIGNAL CHARACTERISTICS

Current–Gain – Bandwidth Product	( $I_C = 20\text{ mA}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 100\text{ MHz}$ )	$f_T$	250	–	MHz
Collector–Base Capacitance	( $V_{CB} = 5.0\text{ Vdc}$ , $I_E = 0$ , $f = 1.0\text{ MHz}$ )	$C_{cb}$	–	6.5	pF
Emitter–Base Capacitance	( $V_{EB} = 0.5\text{ Vdc}$ , $I_C = 0$ , $f = 1.0\text{ MHz}$ )	$C_{eb}$	–	30	pF
Input Impedance	( $I_C = 1.0\text{ mA}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{ie}$	1.0	15	k $\Omega$
Voltage Feedback Ratio	( $I_C = 1.0\text{ mA}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{re}$	0.1	8.0	$\times 10^{-4}$
Small–Signal Current Gain	( $I_C = 1.0\text{ mA}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{fe}$	40	500	–
Output Admittance	( $I_C = 1.0\text{ mA}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{oe}$	1.0	30	$\mu\text{mhos}$

#### SWITCHING CHARACTERISTICS

Delay Time	( $V_{CC} = 30\text{ Vdc}$ , $V_{BE} = 2.0\text{ Vdc}$ , $I_C = 150\text{ mA}$ , $I_{B1} = 15\text{ mA}$ )	$t_d$	–	15	ns
Rise Time		$t_r$	–	20	ns
Storage Time	( $V_{CC} = 30\text{ Vdc}$ , $I_C = 150\text{ mA}$ , $I_{B1} = I_{B2} = 15\text{ mA}$ )	$t_s$	–	225	ns
Fall Time		$t_f$	–	30	ns

1. Pulse Test: Pulse Width  $\leq 300\text{ }\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
2N4401	TO–92	5000 Units / Bulk
2N4401G	TO–92 (Pb–Free)	5000 Units / Bulk
2N4401RLRA	TO–92	2000 / Tape & Reel
2N4401RLRAG	TO–92 (Pb–Free)	2000 / Tape & Reel
2N4401RLRMG	TO–92 (Pb–Free)	2000 / Tape & Ammo Box
2N4401RLRP	TO–92	2000 / Tape & Ammo Box
2N4401RLRPG	TO–92 (Pb–Free)	2000 / Tape & Ammo Box

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## SWITCHING TIME EQUIVALENT TEST CIRCUITS

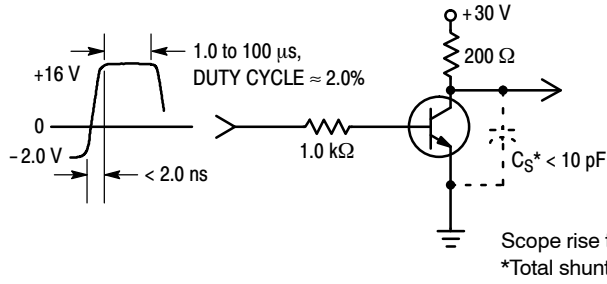


Figure 1. Turn-On Time

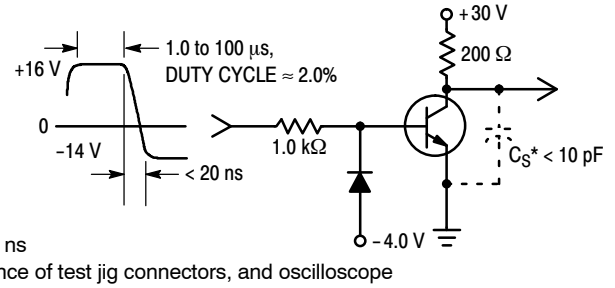


Figure 2. Turn-Off Time

## TRANSIENT CHARACTERISTICS

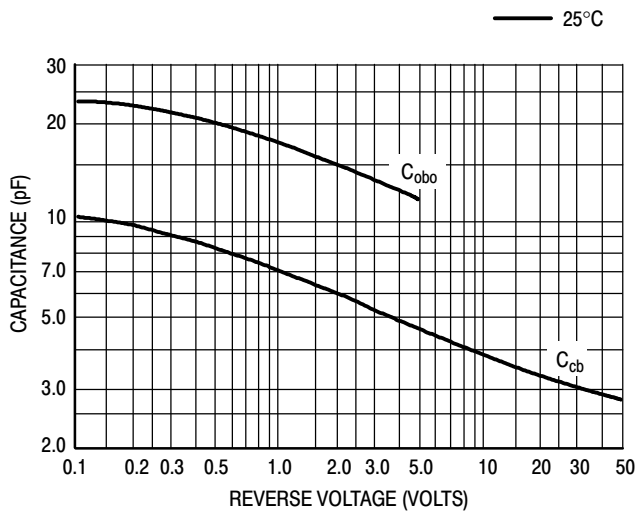


Figure 3. Capacitances

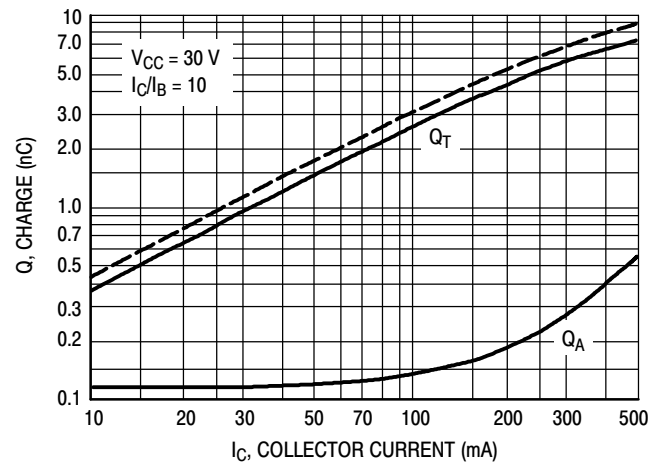


Figure 4. Charge Data

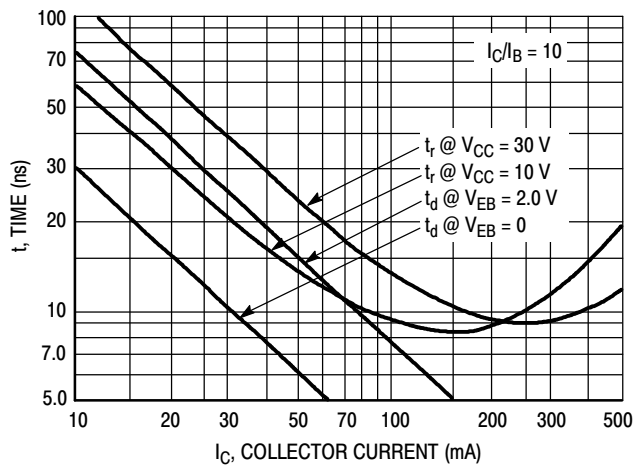


Figure 5. Turn-On Time

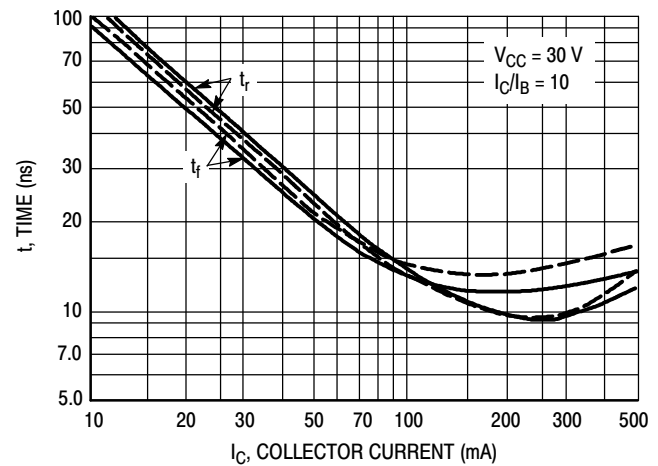


Figure 6. Rise and Fall Times

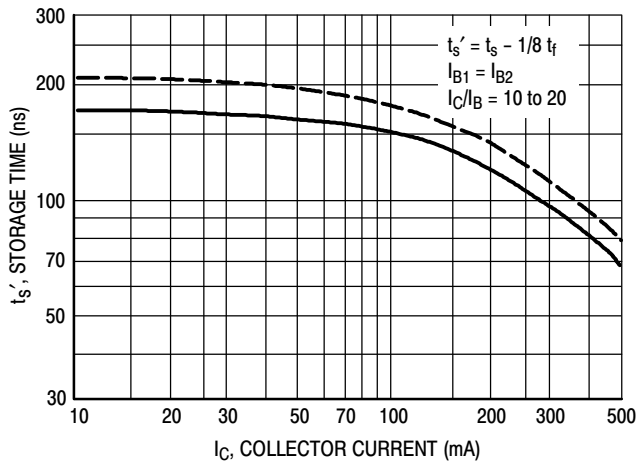


Figure 7. Storage Time

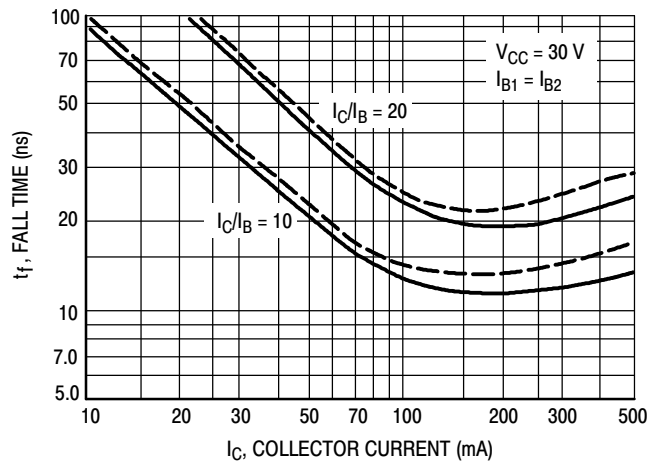


Figure 8. Fall Time

### SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

$V_{CE} = 10 \text{ Vdc}$ ,  $T_A = 25^\circ\text{C}$ ; Bandwidth = 1.0 Hz

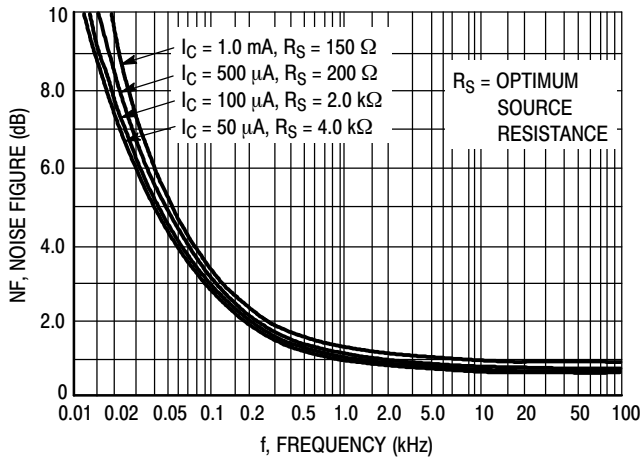


Figure 9. Frequency Effects

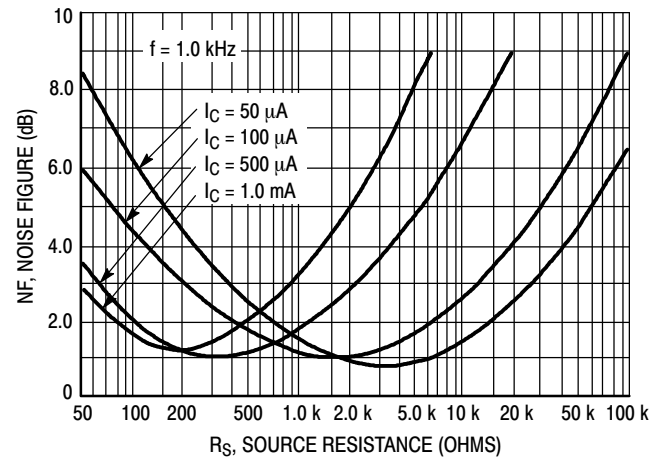


Figure 10. Source Resistance Effects

## 2N4401

### h PARAMETERS

$V_{CE} = 10 \text{ Vdc}$ ,  $f = 1.0 \text{ kHz}$ ,  $T_A = 25^\circ\text{C}$

This group of graphs illustrates the relationship between  $h_{fe}$  and other “h” parameters for this series of transistors. To obtain these curves, a high-gain and a low-gain unit were

selected from the 2N4401 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

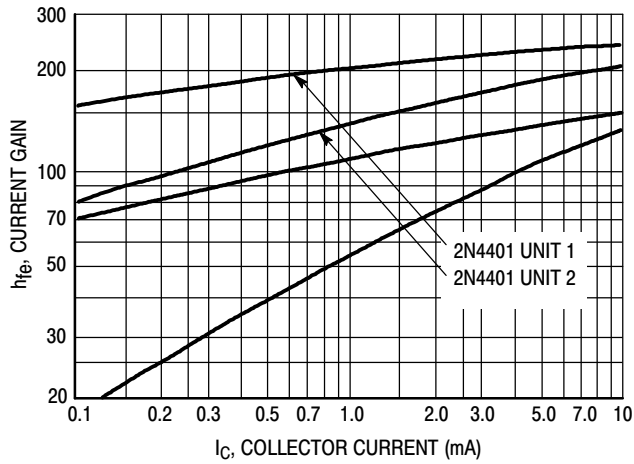


Figure 11. Current Gain

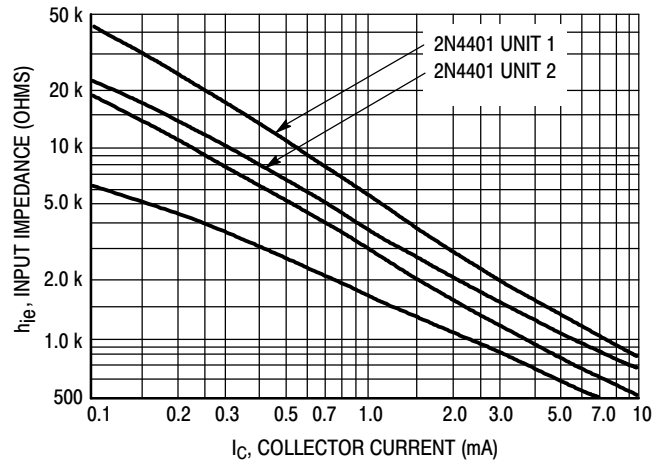


Figure 12. Input Impedance

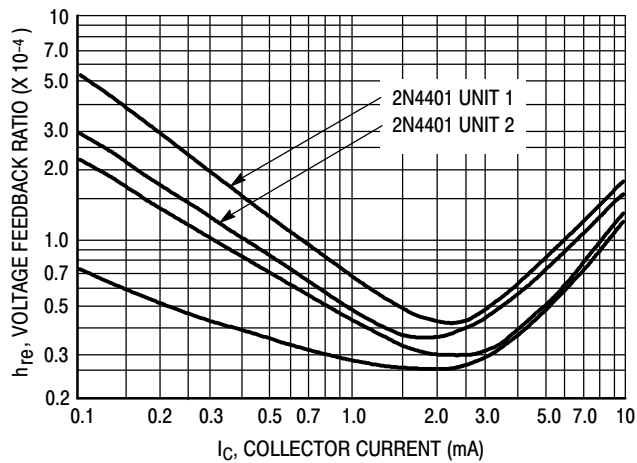


Figure 13. Voltage Feedback Ratio

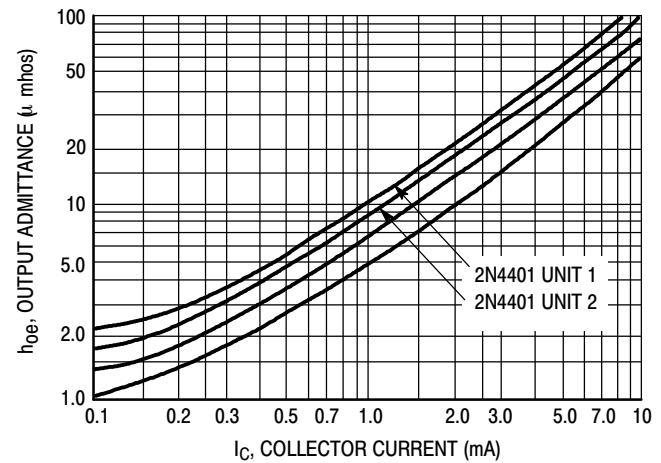


Figure 14. Output Admittance

STATIC CHARACTERISTICS

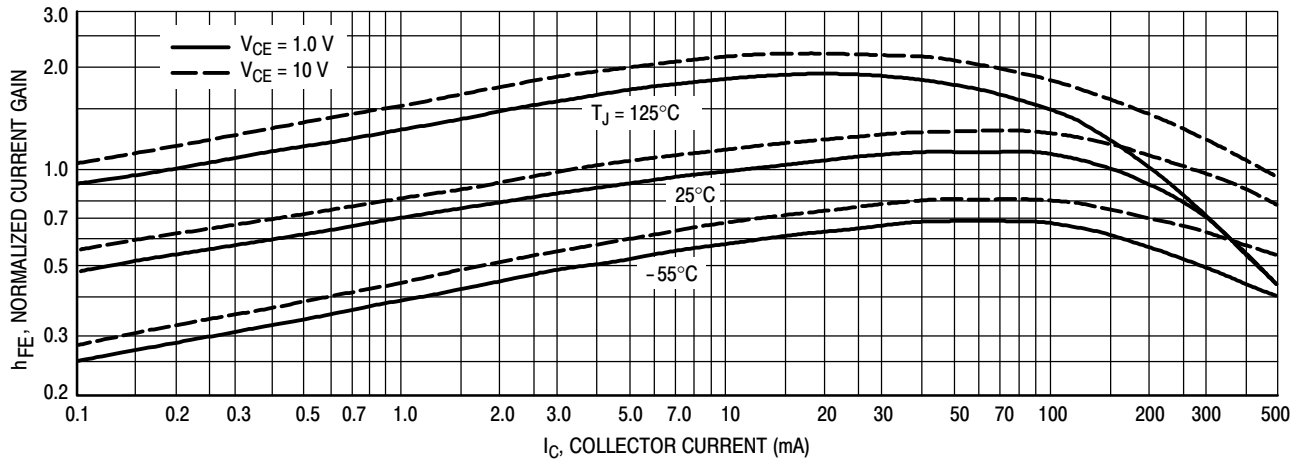


Figure 15. DC Current Gain

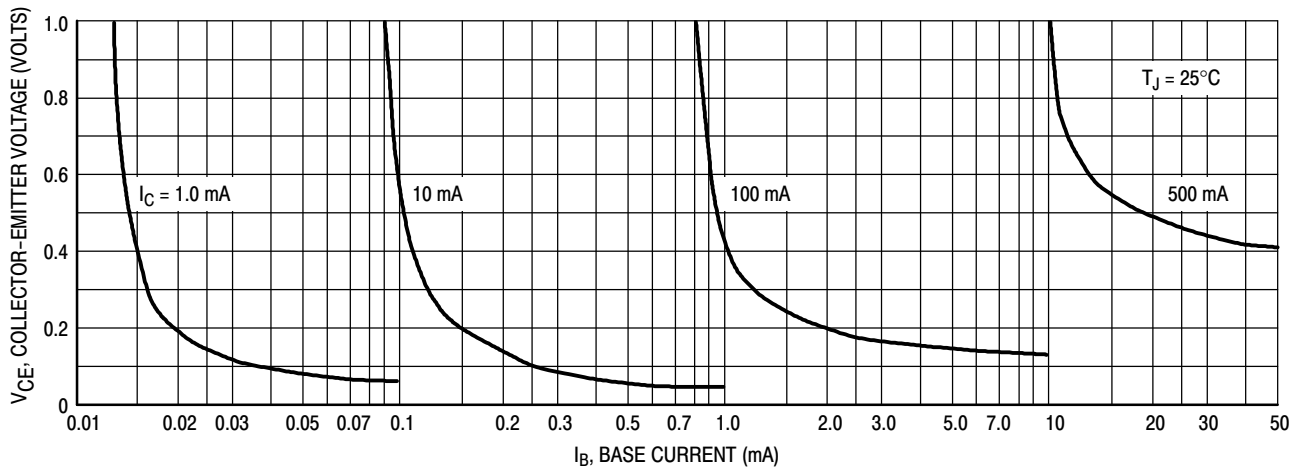


Figure 16. Collector Saturation Region

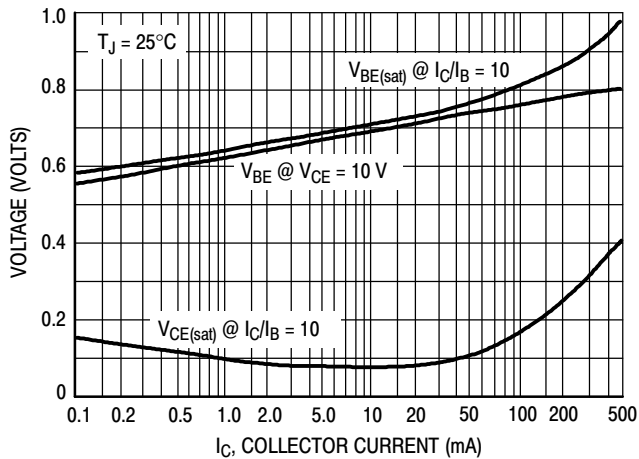


Figure 17. "On" Voltages

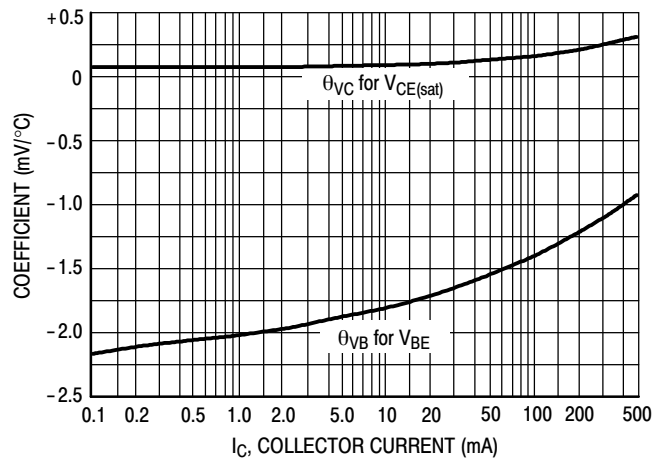
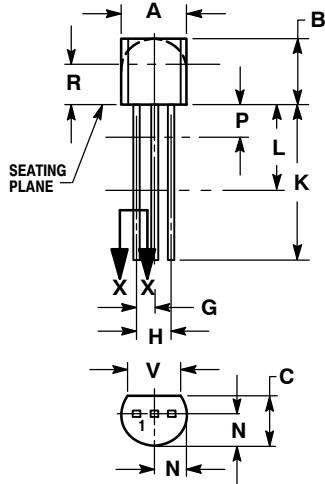


Figure 18. Temperature Coefficients

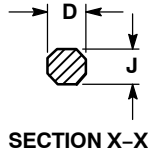
# 2N4401

## PACKAGE DIMENSIONS

### TO-92 (TO-226) CASE 29-11 ISSUE AM



STRAIGHT LEAD  
BULK PACK

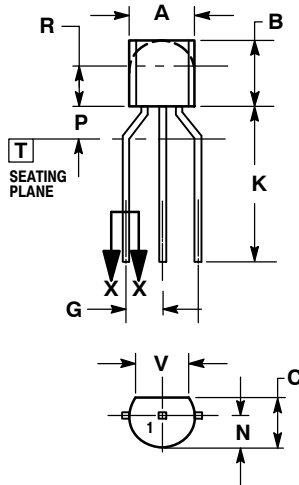


SECTION X-X

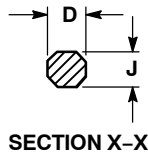
#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD  
TAPE & REEL  
AMMO PACK



SECTION X-X

#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

#### STYLE 1:

1. PIN 1. EMITTER
2. BASE
3. COLLECTOR

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[2N4401TAR](#)

[MMSZ4V3T1G](#)

[2N4401RLRAG.](#)

[2N4401G](#)

[2N4401RLRPG](#)

[2N4401RLRAG](#)

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Cette fiche technique est  
présentée par le fabricant